

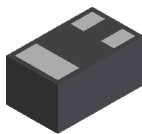
Product Summary

Part Number	R1(NOM)	R2(NOM)	Marking
DDTC144ELP	47kΩ	47kΩ	N6

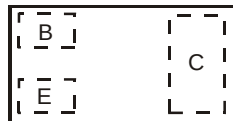
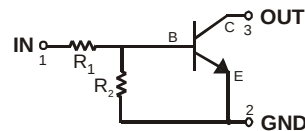
Features

- Epitaxial Planar Die Construction
- Complementary PNP Type Available (DDTA144ELP)
- Ultra-Small Leadless Surface Mount Package
- Ideally Suited for Automated Assembly Processes
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

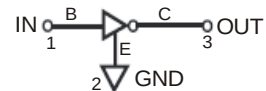
X1-DFN1006-3



Bottom View


 Top View
Pin-Out


Device Symbol

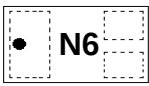
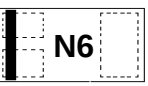
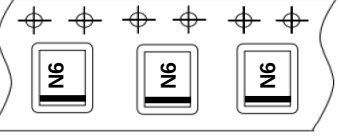

 Equivalent Inverter
Circuit

Ordering Information (Note 4)

Part Number	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DDTC144ELP-7	N6	7	8	3,000
DDTC144ELP-7B	N6	7	8	10,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information

DDTC144ELP-7	<div style="display: flex; justify-content: space-around;"> <div style="text-align: center;">  Top View Dot Denotes Collector Side </div> <div style="text-align: center;">  Top View Bar Denotes Base and Emitter Side </div> </div> <div style="text-align: center;">  </div>
DDTC144ELP-7B	<div style="text-align: center;">  Top View Bar Denotes Base and Emitter Side </div> <div style="text-align: center;">  </div> <div style="text-align: right; margin-top: 20px;"> N6 = Part Marking Code </div>

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Supply Voltage	V _{CC}	50	V
Input Voltage	V _{IN}	-10 to +40	V
Output Current	I _{C(MAX)}	100	mA

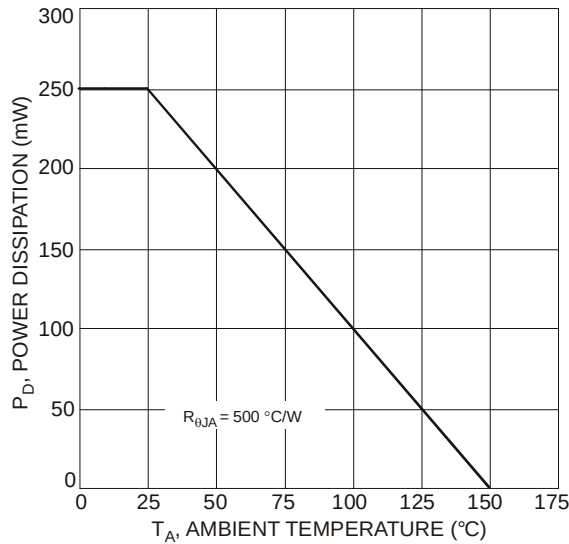
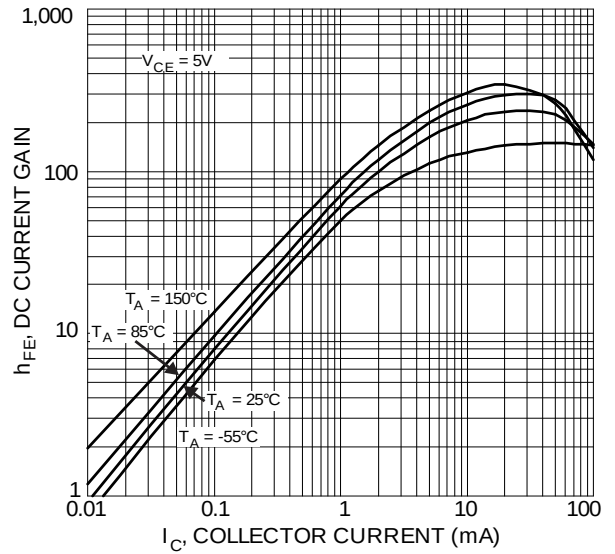
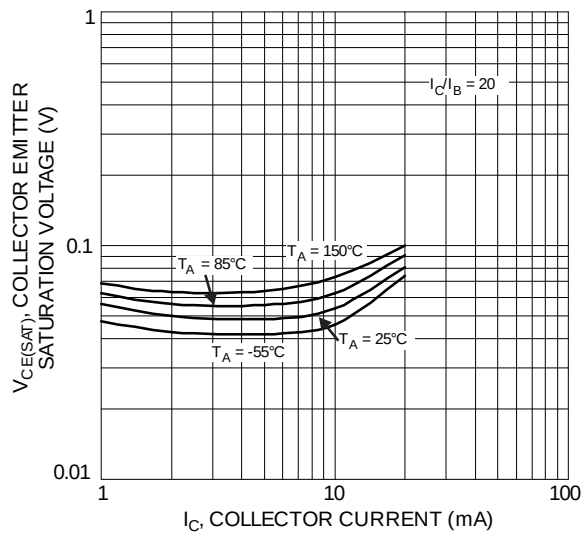
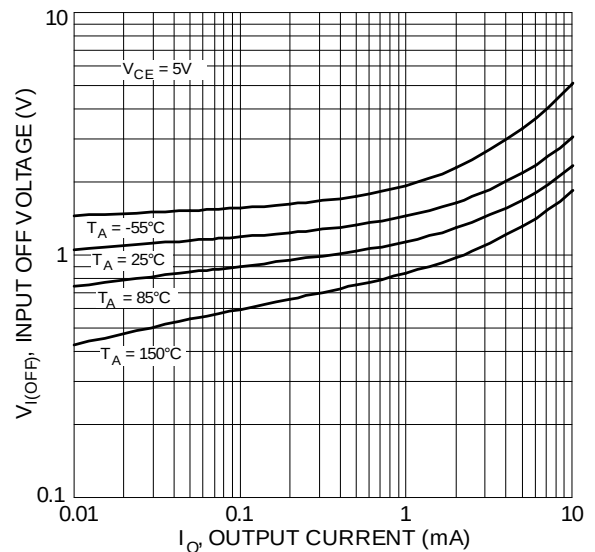
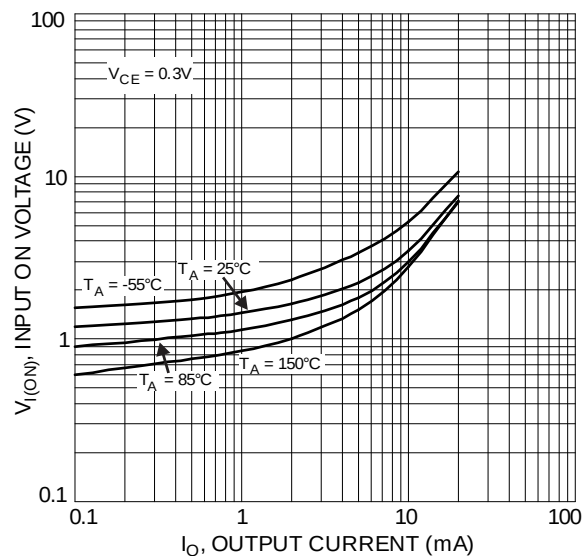
Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	250	mW
Power Deration above 25°C	P _{der}	2	mW/°C
Thermal Resistance, Junction to Ambient Air (Note 5)	R _{θJA}	500	°C/W
Operation and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

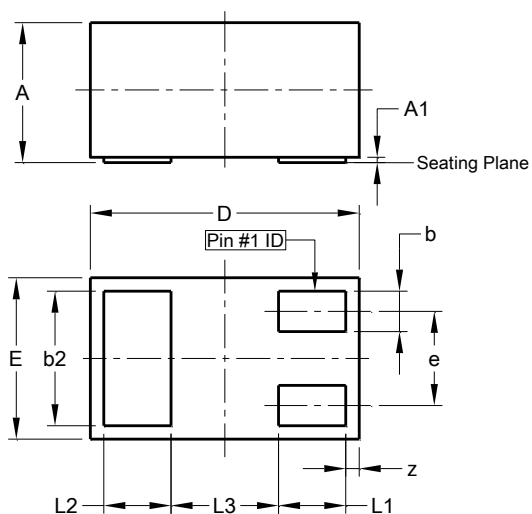
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	50	—	—	V	I _C = 50μA, I _E = 0
Collector-Emitter Breakdown Voltage (Note 6)	BV _{CEO}	50	—	—	V	I _C = 1.0mA, I _B = 0
Collector-Base Cut Off Current	I _{CBO}	—	—	0.5	μA	V _{CB} = 50V, I _E = 0
Input Voltage (Note 6)	V _{I(OFF)}	0.5	1.2	—	V	V _{CE} = 5V, I _O = 100μA
	V _{I(ON)}	—	1.6	3		V _{CE} = 0.3V, I _O = 2mA
Output Voltage (Note 6)	V _{O(ON)}	—	—	0.3	V	I _O /I _I = 10mA/0.5mA
Input Current	I _I	—	—	0.18	mA	V _I = 5V
Output Current	I _{O(OFF)}	—	—	0.5	μA	V _{CC} = 50V, V _I = 0V
DC Current Gain (Note 6)	G ₁	68	—	—	—	V _O = 5V, I _O = 5mA
Input Resistance	R ₁	32.9	47	61.1	kΩ	—
Resistance Ratio	R ₂ /R ₁	0.8	1	1.2	—	—
Transition Frequency (Note 7)	f _T	—	250	—	MHz	V _{CE} = 10V, I _E = 5mA, f = 100MHz

- Notes:
5. For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink.
 6. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.
 7. Characteristics of transistor only.



Package Outline Dimensions

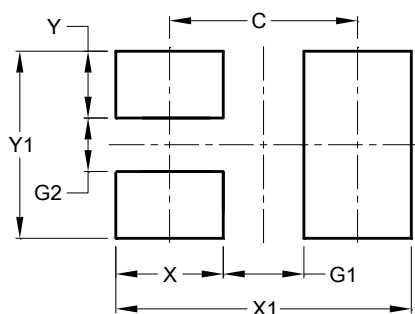
Please see <http://www.diodes.com/package-outlines.html> for the latest version.



X1-DFN1006-3			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0.00	0.05	0.03
b	0.10	0.20	0.15
b2	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.35
L1	0.20	0.30	0.25
L2	0.20	0.30	0.25
L3	-	-	0.40
z	0.02	0.08	0.05
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



Dimensions	Value (in mm)
C	0.70
G1	0.30
G2	0.20
X	0.40
X1	1.10
Y	0.25
Y1	0.70

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